

AMENDMENT TRANSMITTAL LETTER (Large Entity)Applicant(s): **Hiroyuki Kawano**

Docket No.

OKI.304

Serial No.

10/062,505

Filing Date

February 5, 2002

Examiner

S. Geyer

Group Art Unit

2829

INVENTION: METHOD OF MANUFACTURING A SEMICONDUCTOR DEVICE INCLUDING ETCHING OF A PERIPHERAL AREA BEFORE CHEMICAL-MECHANICAL POLISHING

TO THE COMMISSIONER FOR PATENTS:

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED

	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	11 -	20 =	0 x	\$18.00	\$0.00
INDEP. CLAIMS	1 -	3 =	0 x	\$86.00	\$0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0.00

- ☒ No additional fee is required for amendment.
- ☐ Please charge Deposit Account No. _____ in the amount of _____
- ☐ A check in the amount of _____ to cover the filing fee is enclosed.
- ☒ The Director is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. **50-0238**
- ☒ Any additional filing fees required under 37 C.F.R. 1.16.
- ☒ Any patent application processing fees under 37 CFR 1.17.

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Dated: **December 15, 2003**

Signature

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I certify that this document and fee is being deposited on _____ with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

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cc:

Serial No. 10/062,505

OKI.304

Amendment dated December 15, 2003

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Office PATENT APPLICATION of

Hiroyuki Kawano

Group Art Unit: 2829

Serial No.: 10/062,505

Examiner: S. Geyer

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For: METHOD OF MANUFACTURING A SEMICONDUCTOR DEVICE INCLUDING
ETCHING OF A PERIPHERAL AREA BEFORE CHEMICAL-MECHANICAL
POLISHING

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AMENDMENT

U.S. Patent and Trademark Office
2011 South Clark Place
Customer Window, **Mail Stop Non-Fee Amendment**
Crystal Plaza Two, Lobby, Room 1B03
Arlington, VA 22202

Date: December 15, 2003

Sir:

In response to the Office Action dated September 18, 2003, the following
amendments and remarks are respectfully submitted in connection with the above-
identified application.

Amendments to the Claims are reflected in the listing of claims which begins
on page 2 of this paper.

Remarks/Arguments begin on page 6 of this paper.